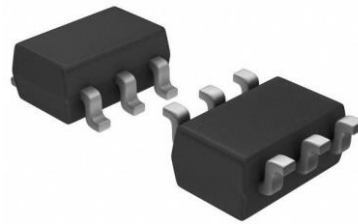


**WNMD2176**
**Dual N-Channel, 20V, 2.6A, Power MOSFET**
[www.sh-willsemi.com](http://www.sh-willsemi.com)

$V_{DS}$ (V)	Typical $R_{DS(on)}$ (m $\Omega$ )
20	56@ $V_{GS}=4.5V$
	76@ $V_{GS}=2.5V$
ESD Protected	


**Descriptions**

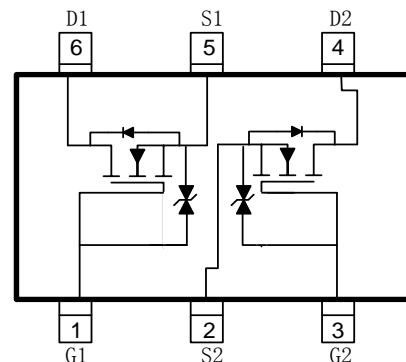
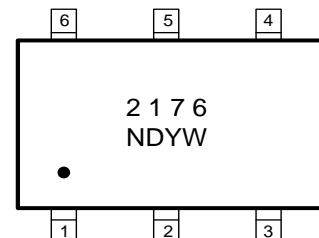
The WNMD2176 is N-Channel enhancement MOS Field Effect Transistor. Uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit. Standard Product WNMD2176 is Pb-free.

**Features**

- Trench Technology
- Supper high density cell design
- Excellent ON resistance
- Extremely Low Threshold Voltage
- Small package SOT-23-6L

**Applications**

- Driver for Relay, Solenoid, Motor, LED etc.
- Power supply converters circuit
- Load/Power Switching for portable device

**SOT-23-6L**

**Pin configuration (Top view)**


2176 = Device Code  
 ND = Special Code  
 Y = Year  
 W = Week(A~z)

**Marking**
**Order information**

Device	Package	Shipping
WNMD2176-6/TR	SOT-23-6L	3000/Tape&Reel

**Absolute Maximum ratings**

Parameter	Symbol	10 s	Steady State	Unit	
Drain-Source Voltage	$V_{DS}$	20		V	
Gate-Source Voltage	$V_{GS}$	$\pm 10$			
Continuous Drain Current <sup>a</sup>	$I_D$	$T_A=25^{\circ}\text{C}$	2.8	2.6	A
		$T_A=70^{\circ}\text{C}$	2.3	2.1	
Maximum Power Dissipation <sup>a</sup>	$P_D$	$T_A=25^{\circ}\text{C}$	1.1	0.9	W
		$T_A=70^{\circ}\text{C}$	0.7	0.6	
Continuous Drain Current <sup>b</sup>	$I_D$	$T_A=25^{\circ}\text{C}$	2.6	2.3	A
		$T_A=70^{\circ}\text{C}$	2.0	1.9	
Maximum Power Dissipation <sup>b</sup>	$P_D$	$T_A=25^{\circ}\text{C}$	0.9	0.7	W
		$T_A=70^{\circ}\text{C}$	0.5	0.4	
Pulsed Drain Current <sup>c</sup>	$I_{DM}$	7		A	
Operating Junction Temperature	$T_J$	150		$^{\circ}\text{C}$	
Lead Temperature	$T_L$	260		$^{\circ}\text{C}$	
Storage Temperature Range	$T_{stg}$	-55 to 150		$^{\circ}\text{C}$	

**Thermal resistance ratings**

Single Operation					
Parameter	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient Thermal Resistance <sup>a</sup>	$R_{\theta JA}$	$t \leq 10 \text{ s}$	90	108	$^{\circ}\text{C}/\text{W}$
		Steady State	110	130	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	$R_{\theta JA}$	$t \leq 10 \text{ s}$	105	128	
		Steady State	133	158	
Junction-to-Case Thermal Resistance	$R_{\theta JC}$	60	75		

a Surface mounted on FR4 Board using 1 square inch pad size, 1oz copper

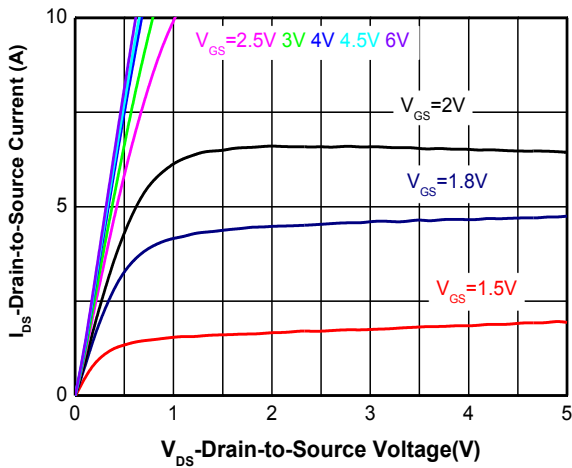
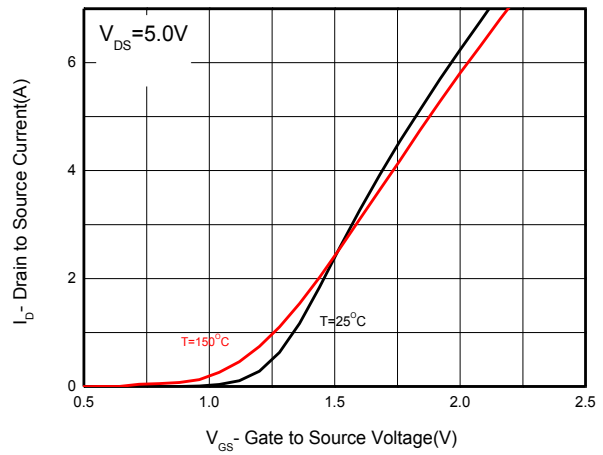
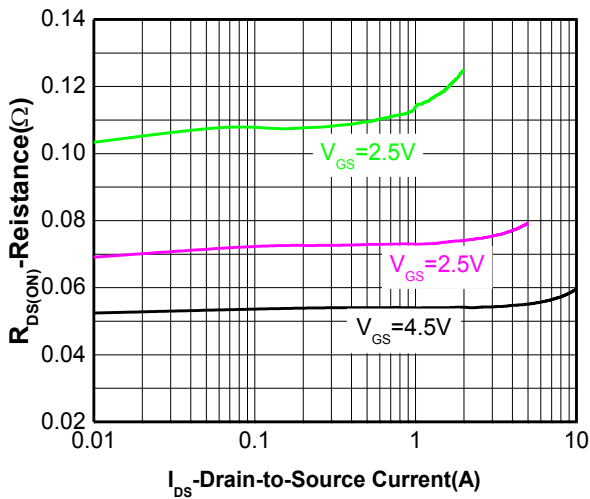
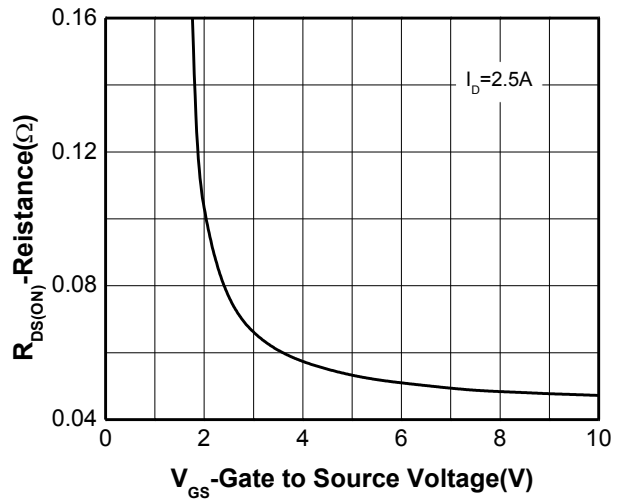
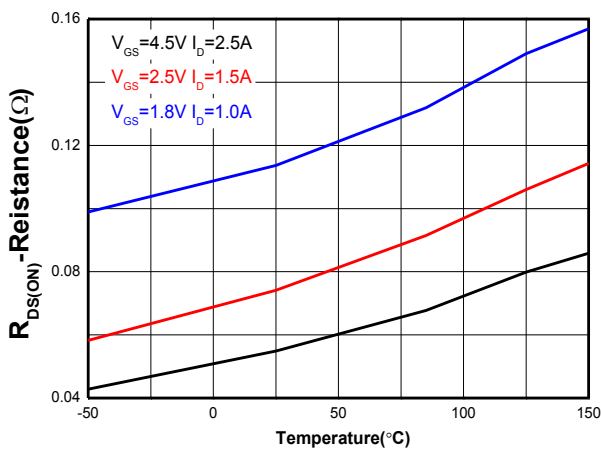
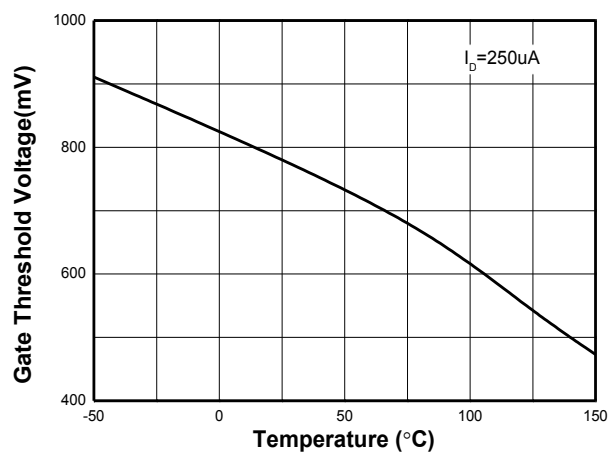
b Surface mounted on FR4 board using minimum pad size, 1oz copper

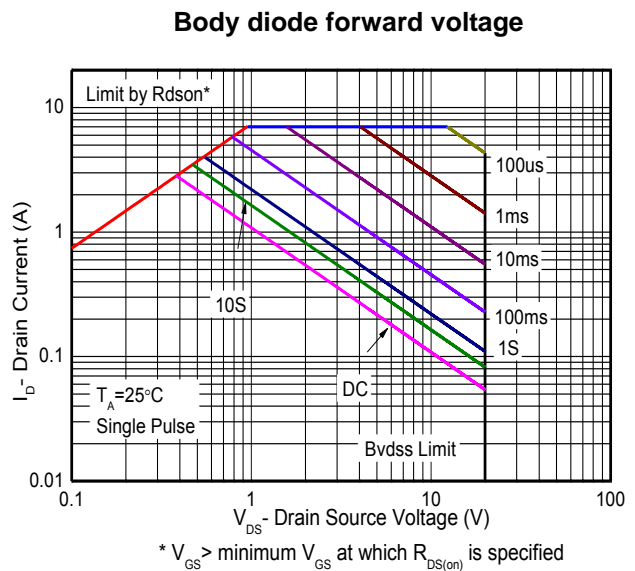
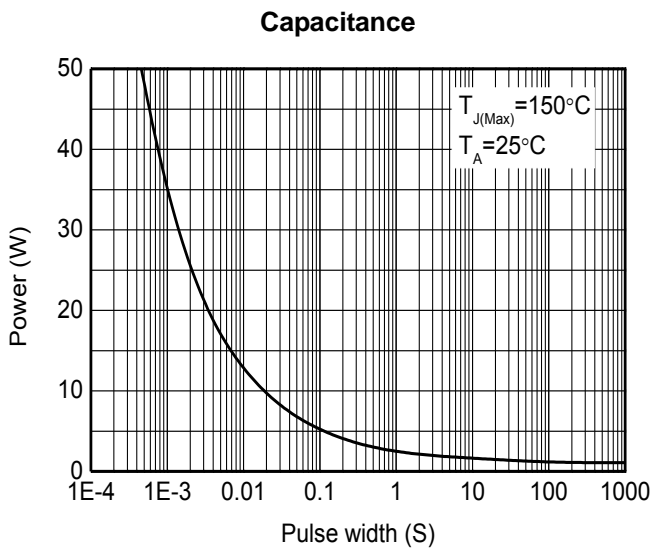
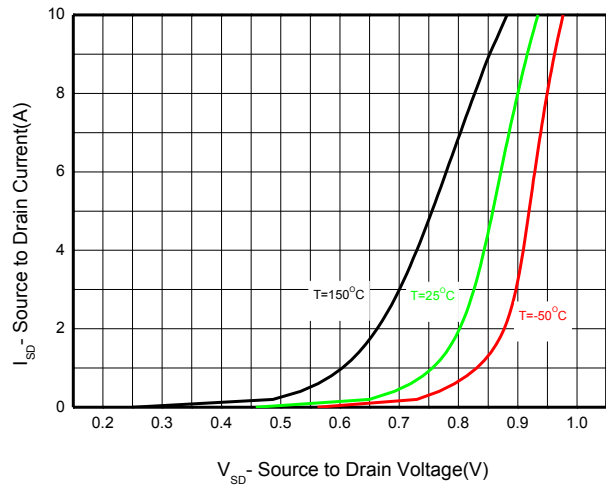
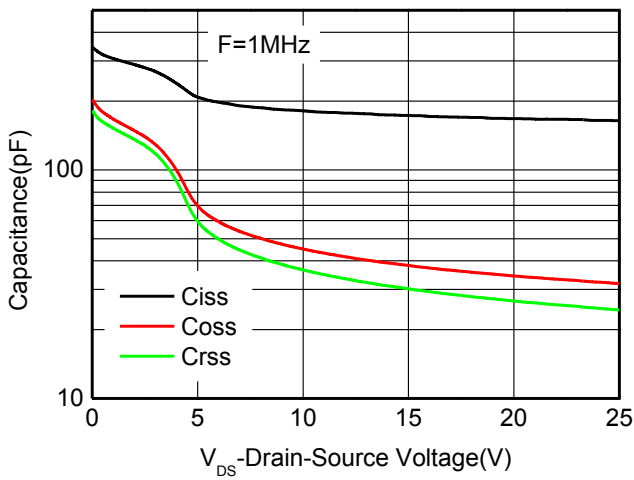
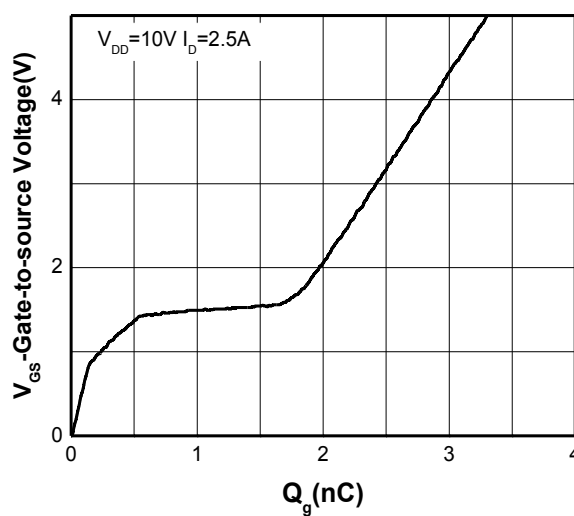
c Repetitive rating, pulse width limited by junction temperature,  $t_p=10\mu\text{s}$ , Duty Cycle=1%

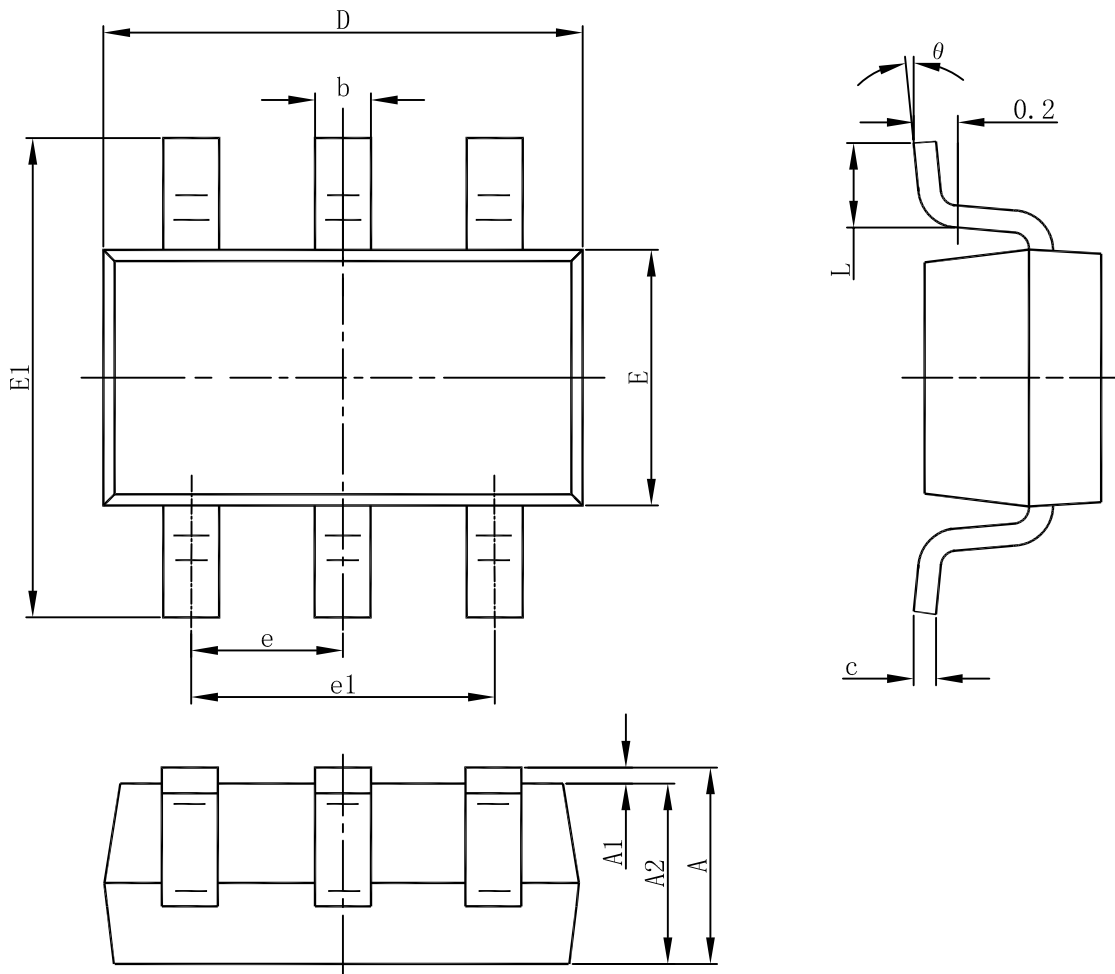
d Repetitive rating, pulse width limited by junction temperature  $T_J=150^{\circ}\text{C}$ .

**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	20.5			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 16\text{ V}, V_{GS} = 0\text{ V}$			100	nA
Gate-to-source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 10\text{ V}$			$\pm 5$	$\mu\text{A}$
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	0.5	0.78	1.0	V
Drain-to-source On-resistance	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}, I_D = 2.5\text{ A}$	40	55	90	m $\Omega$
		$V_{GS} = 3.1\text{ V}, I_D = 2.0\text{ A}$	45	66	110	
		$V_{GS} = 2.5\text{ V}, I_D = 1.5\text{ A}$	51	75	130	
Forward Transconductance	$g_{FS}$	$V_{DS} = 5.0\text{ V}, I_D = 7.0\text{ A}$		11	16	S
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	$C_{ISS}$	$V_{GS} = 0\text{ V}, f = 1\text{ MHz}, V_{DS} = 10\text{ V}$		190		pF
Output Capacitance	$C_{OSS}$			45		
Reverse Transfer Capacitance	$C_{RSS}$			36		
Total Gate Charge	$Q_{G(TOT)}$	$V_{GS} = 4.5\text{ V}, V_{DS} = 10\text{ V}, I_D = 2.5\text{ A}$		3.1		nC
Threshold Gate Charge	$Q_{G(TH)}$			0.1		
Gate-to-Source Charge	$Q_{GS}$			0.55		
Gate-to-Drain Charge	$Q_{GD}$			1.1		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	$t_d(ON)$	$V_{GS} = 4.5\text{ V}, V_{DS} = 10\text{ V}, R_L = 10\Omega, R_G = 6\Omega$		12.2		ns
Rise Time	$t_r$			12.5		
Turn-Off Delay Time	$t_d(OFF)$			29.6		
Fall Time	$t_f$			9.8		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{ V}, I_S = 1.0\text{ A}$			1.5	V

**Typical Characteristics (Ta=25°C, unless otherwise noted)**

**Output characteristics**

**Transfer characteristics**

**On-Resistance vs. Drain current**

**On-Resistance vs. Gate-to-Source voltage**

**On-Resistance vs. Junction temperature**

**Threshold voltage vs. Temperature**


**Single pulse power**
**Safe operating power**

**Transient thermal response (Junction-to-Ambient)**

**Package outline dimensions**
**SOT-23-6L**


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°